



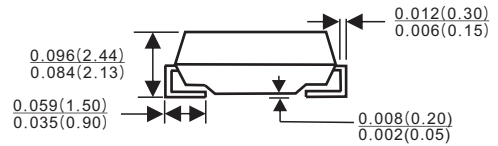
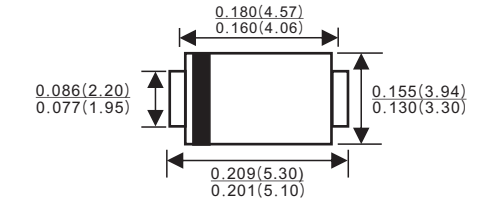
### Features

- ✧ Plastic package has underwriters laborator flammability classification 94V-0
- ✧ For surface mounted applications
- ✧ Low profile package
- ✧ Built-in strain relief, ideal for automated placement
- ✧ Glass passivated chip junction
- ✧ High temperature soldering: 250°C/10 seconds at terminals

**REVERSE VOLTAGE: 50 --- 1000 V**

**CURRENT: 1.0A**

**SMB/DO-214AA**



Dimensions in inches and (millimeters)

### Mechanical Data

- ✧ Case: JEDEC DO-214AA, molded plastic over passivated chip
- ✧ Polarity: color band denotes cathode end
- ✧ Weight: 0.003 ounces, 0.093 gram

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

Parameter	Symbol	RA1AB	RS1BD	RS1DB	RS1GB	RS1JB	RS1KB	RS1MB	
Marking code		RS1A	RS1B	RS1D	RS1G	RS1J	RS1K	RS1M	UNITS
Maximum recurrent peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RWS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_J=90^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	1.30							V
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	$I_R$	5.0 50.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	150				250	500		ns
Typical junction capacitance (NOTE 2)	$C_J$	10					7.0		pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JL}$	105 32							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	- 55 ----- + 150							$^\circ\text{C}$

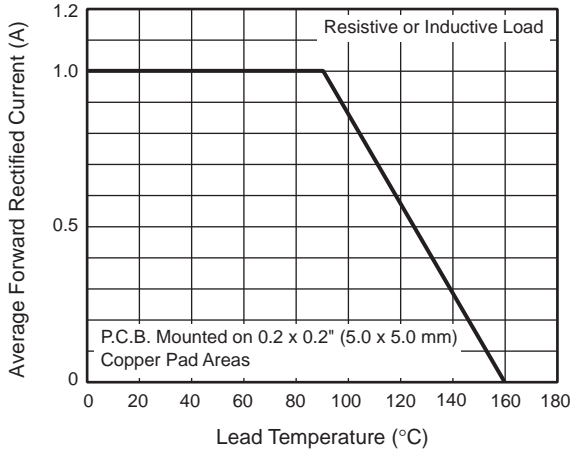
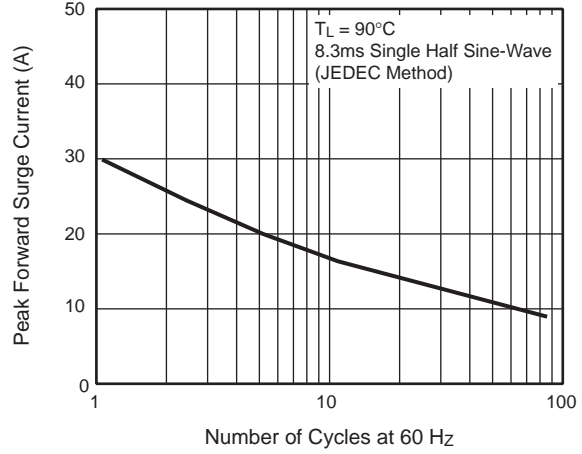
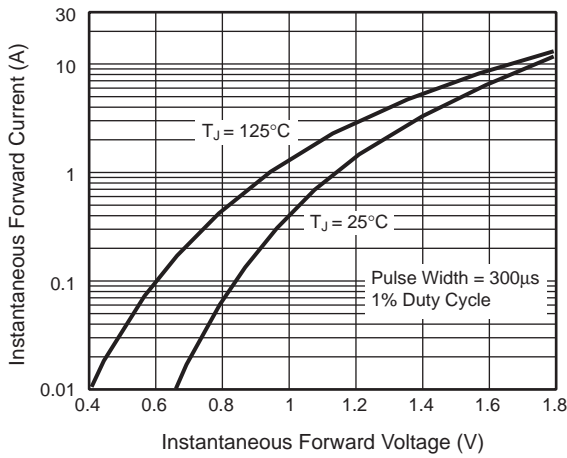
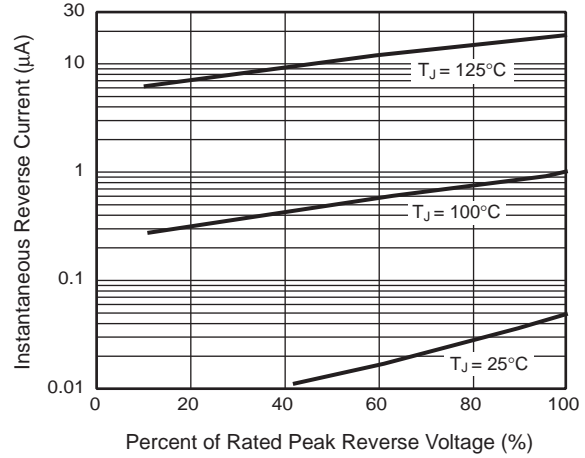
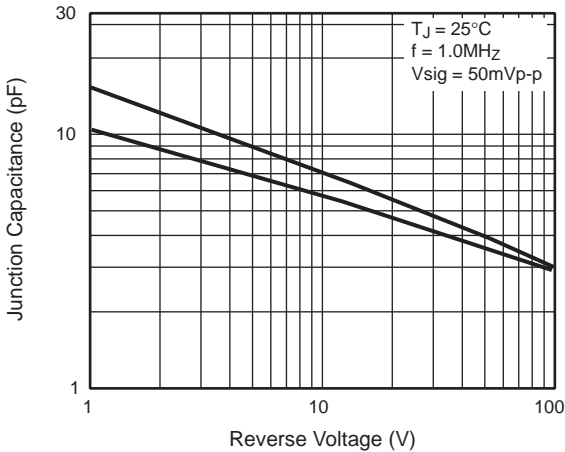
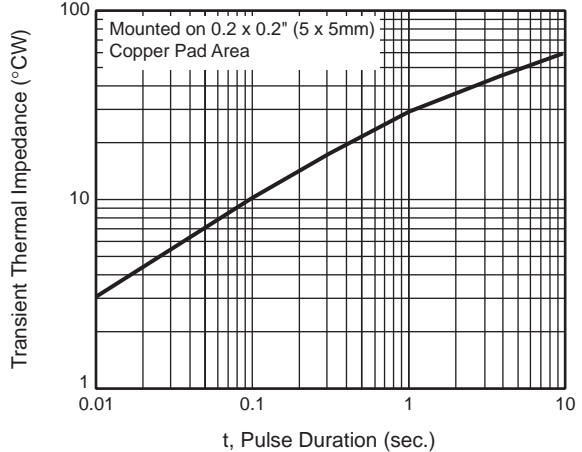
NOTE: 1. Reverse recovery time test conditions:  $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$

2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.2"X0.2"(5.0X5.0mm<sup>2</sup>) copper pad areas



## Ratings AND Characteristic Curves

**Fig. 1 — Forward Current Derating Curve**

**Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current**

**Fig. 3 — Typical Instantaneous Forward Characteristics**

**Fig. 4 — Typical Reverse Characteristics**

**Fig. 5 — Typical Junction Capacitance**

**Fig. 6 — Typical Transient Thermal Impedance**


PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMB	3000/REEL	48000	36X35.8X36.5	12.00	11.00